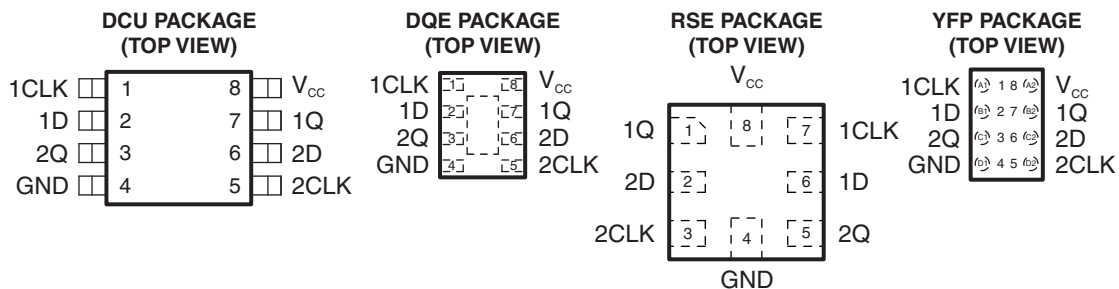


## LOW-POWER DUAL POSITIVE EDGE-TRIGGERED D-TYPE FLIP-FLOP

 Check for Samples: [SN74AUP2G79](#)

### FEATURES

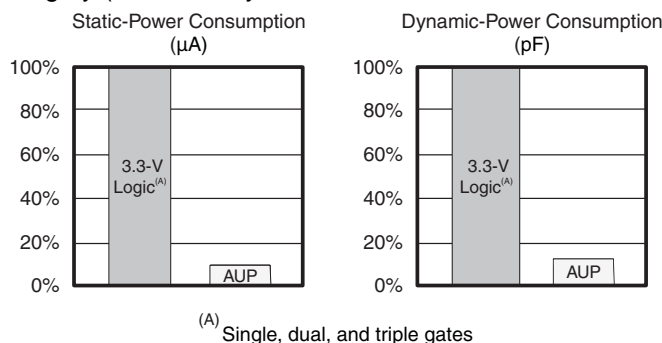
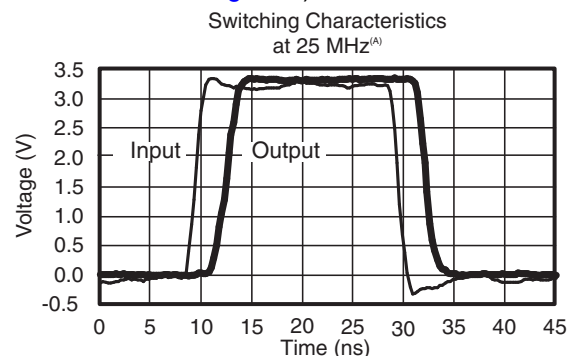
- Available in the Texas Instruments NanoStar™ Package
- Low Static-Power Consumption ( $I_{CC} = 0.9 \mu\text{A}$  Maximum)
- Low Dynamic-Power Consumption ( $C_{pd} = 3 \text{ pF}$  Typ at 3.3 V)
- Low Input Capacitance ( $C_i = 1.5 \text{ pF}$  Typical)
- Low Noise – Overshoot and Undershoot <10% of  $V_{CC}$
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Wide Operating  $V_{CC}$  Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 4 \text{ ns}$  Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

### DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire  $V_{CC}$  range of 0.8 V to 3.6 V, resulting in increased battery life (see [Figure 1](#)). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in [Figure 2](#)).


**Figure 1. AUP – The Lowest-Power Family**

<sup>(A)</sup> SN74AUP2Gxx data at  $C_L = 15 \text{ pF}$ .

**Figure 2. Excellent Signal Integrity**


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

When data at the data (D) input meets the setup time requirement, the data is transferred to the Q output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

NanoStar™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**ORDERING INFORMATION<sup>(1)</sup>**

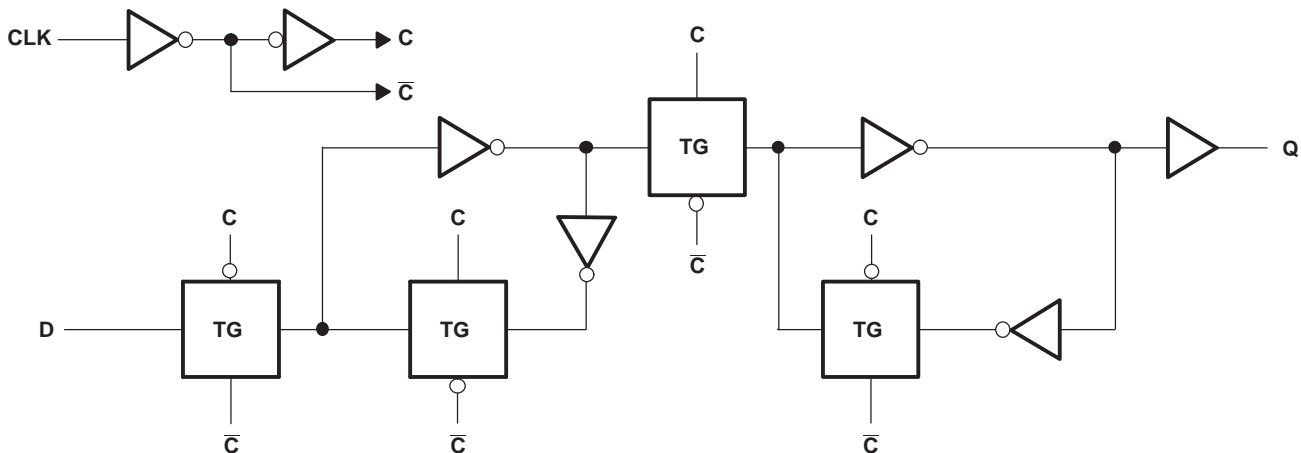
T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
-40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YFP (Pb-free)	Reel of 3000	SN74AUP2G79YFPR	_ _ H W _
	uQFN – DQE	Reel of 5000	SN74AUP2G79DQER	PT
	QFN – RSE	Reel of 5000	SN74AUP2G79RSEER	PT
	SSOP – DCU	Reel of 3000	SN74AUP2G79DCUR	H79_

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).
- (3) DCU: The actual top-side marking has one additional character that designates the wafer fab/assembly site.  
YFP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

**FUNCTION TABLE**

INPUTS		OUTPUT Q
CLK	D	
↑	H	H
↑	L	L
L	X	Q <sub>0</sub>

**LOGIC DIAGRAM, EACH FLIP-FLOP (POSITIVE LOGIC)**



Pin numbers shown are for the DCU and DQE packages.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			<b>MIN</b>	<b>MAX</b>	<b>UNIT</b>
$V_{CC}$	Supply voltage range		-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>		-0.5	4.6	V
$V_O$	Output voltage range in the high or low state <sup>(2)</sup>		-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA
$I_O$	Continuous output current			$\pm 20$	mA
	Continuous current through $V_{CC}$ or GND			$\pm 50$	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DCU package		220	°C/W
		DQE package		261	
		RSE package		253	
		YFP package		132	
$T_{stg}$	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	0.8	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.1 V to 1.95 V	0.65 × V <sub>CC</sub>	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	
		V <sub>CC</sub> = 3 V to 3.6 V	2	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 0.8 V	0	V
		V <sub>CC</sub> = 1.1 V to 1.95 V	0.35 × V <sub>CC</sub>	
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	
		V <sub>CC</sub> = 3 V to 3.6 V	0.9	
V <sub>I</sub>	Input voltage	0	3.6	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 0.8 V	–20	μA
		V <sub>CC</sub> = 1.1 V	–1.1	
		V <sub>CC</sub> = 1.4 V	–1.7	
		V <sub>CC</sub> = 1.65	–1.9	
		V <sub>CC</sub> = 2.3 V	–3.1	
		V <sub>CC</sub> = 3 V	–4	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 0.8 V	20	μA
		V <sub>CC</sub> = 1.1 V	1.1	
		V <sub>CC</sub> = 1.4 V	1.7	
		V <sub>CC</sub> = 1.65 V	1.9	
		V <sub>CC</sub> = 2.3 V	3.1	
		V <sub>CC</sub> = 3 V	4	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 0.8 V to 3.6 V	200	ns/V
T <sub>A</sub>	Operating free-air temperature	–40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –20 μA	0.8 V to 3.6 V	V <sub>CC</sub> – 0.1			V <sub>CC</sub> – 0.1		V
	I <sub>OH</sub> = –1.1 mA	1.1 V	0.75 × V <sub>CC</sub>			0.7 × V <sub>CC</sub>		
	I <sub>OH</sub> = –1.7 mA	1.4 V	1.11			1.03		
	I <sub>OH</sub> = –1.9 mA	1.65 V	1.32			1.3		
	I <sub>OH</sub> = –2.3 mA	2.3 V	2.05			1.97		
	I <sub>OH</sub> = –3.1 mA		1.9			1.85		
	I <sub>OH</sub> = –2.7 mA	3 V	2.72			2.67		
	I <sub>OH</sub> = –4 mA		2.6			2.55		
V <sub>OL</sub>	I <sub>OL</sub> = 20 μA	0.8 V to 3.6 V	0.1			0.1		V
	I <sub>OL</sub> = 1.1 mA	1.1 V	0.3 × V <sub>CC</sub>			0.3 × V <sub>CC</sub>		
	I <sub>OL</sub> = 1.7 mA	1.4 V	0.31			0.37		
	I <sub>OL</sub> = 1.9 mA	1.65 V	0.31			0.35		
	I <sub>OL</sub> = 2.3 mA	2.3 V	0.31			0.33		
	I <sub>OL</sub> = 3.1 mA		0.44			0.45		
	I <sub>OL</sub> = 2.7 mA	3 V	0.31			0.33		
	I <sub>OL</sub> = 4 mA		0.44			0.45		
I <sub>i</sub>	A or B input	V <sub>i</sub> = GND to 3.6 V	0 V to 3.6 V			0.1	0.5	μA
I <sub>off</sub>		V <sub>i</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V			0.2	0.6	μA
ΔI <sub>off</sub>		V <sub>i</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V to 0.2 V			0.2	0.6	μA
I <sub>CC</sub>		V <sub>i</sub> = GND or (V <sub>CC</sub> to 3.6 V), I <sub>O</sub> = 0	0.8 V to 3.6 V			0.5	0.9	μA
ΔI <sub>CC</sub>		V <sub>i</sub> = V <sub>CC</sub> – 0.6 V <sup>(1)</sup> , I <sub>O</sub> = 0	3.3 V			40	50	μA
C <sub>i</sub>	V <sub>i</sub> = V <sub>CC</sub> or GND	0 V	1.5					pF
		3.6 V	1.5					
C <sub>o</sub>	V <sub>O</sub> = GND	0 V	3					pF

 (1) One input at V<sub>CC</sub> – 0.6 V, other input at V<sub>CC</sub> or GND

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 4](#))

		V <sub>CC</sub>	T <sub>A</sub> = 25°C	T <sub>A</sub> = -40°C to 85°C	UNIT
			TYP	MIN MAX	
f <sub>clock</sub>	Clock frequency	0.8 V		20	MHz
		1.2 V ± 0.1 V		80	
		1.5 V ± 0.1 V		100	
		1.8 V ± 0.15 V		140	
		2.5 V ± 0.2 V		210	
		3.3 V ± 0.3 V		260	
t <sub>w</sub>	Pulse duration, CLK high or low	0.8 V		4.8	ns
		1.2 V ± 0.1 V		2.2	
		1.5 V ± 0.1 V		1.5	
		1.8 V ± 0.15 V		1.6	
		2.5 V ± 0.2 V		1.7	
		3.3 V ± 0.3 V		1.9	
t <sub>su</sub>	Data high	0.8 V	2.9	4.2	ns
		1.2 V ± 0.1 V		1.4	
		1.5 V ± 0.1 V		1	
		1.8 V ± 0.15 V		0.9	
		2.5 V ± 0.2 V		0.7	
		3.3 V ± 0.3 V		0.6	
	Data low	0.8 V	3.5	5.3	
		1.2 V ± 0.1 V		1.8	
		1.5 V ± 0.1 V		1.2	
		1.8 V ± 0.15 V		1.1	
		2.5 V ± 0.2 V		1	
		3.3 V ± 0.3 V		1	
t <sub>h</sub>	Hold time, data after CLK↑	0.8 V	0	0	ns
		1.2 V ± 0.1 V		0	
		1.5 V ± 0.1 V		0	
		1.8 V ± 0.15 V		0	
		2.5 V ± 0.2 V		0	
		3.3 V ± 0.3 V		0	

**SWITCHING CHARACTERISTICS**

 over recommended operating free-air temperature range,  $C_L = 5 \text{ pF}$  (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V	93			90		MHz
			$1.2 \text{ V} \pm 0.1 \text{ V}$	199			220		
			$1.5 \text{ V} \pm 0.1 \text{ V}$	250			230		
			$1.8 \text{ V} \pm 0.15 \text{ V}$	271			240		
			$2.5 \text{ V} \pm 0.2 \text{ V}$	280			250		
			$3.3 \text{ V} \pm 0.3 \text{ V}$	280			260		
$t_{pd}$	CLK	Q	0.8 V	15.9					ns
			$1.2 \text{ V} \pm 0.1 \text{ V}$	3.7	6.9	11	2.6	13.1	
			$1.5 \text{ V} \pm 0.1 \text{ V}$	3	4.8	7.6	2	8.8	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	2.4	3.8	6.1	1.5	7.1	
			$2.5 \text{ V} \pm 0.2 \text{ V}$	1.8	2.7	4.4	1.1	5	
			$3.3 \text{ V} \pm 0.3 \text{ V}$	1.5	2.1	3.6	0.9	4	

**SWITCHING CHARACTERISTICS**

 over recommended operating free-air temperature range,  $C_L = 10 \text{ pF}$  (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V	62			50		MHz
			$1.2 \text{ V} \pm 0.1 \text{ V}$	147			160		
			$1.5 \text{ V} \pm 0.1 \text{ V}$	189			200		
			$1.8 \text{ V} \pm 0.15 \text{ V}$	180			240		
			$2.5 \text{ V} \pm 0.2 \text{ V}$	260			250		
			$3.3 \text{ V} \pm 0.3 \text{ V}$	280			260		
$t_{pd}$	CLK	Q	0.8 V	18					ns
			$1.2 \text{ V} \pm 0.1 \text{ V}$	4.3	7.8	12.3	3.2	14.4	
			$1.5 \text{ V} \pm 0.1 \text{ V}$	3.5	5.5	8.4	2.5	9.8	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	2.8	4.4	6.8	1.9	8	
			$2.5 \text{ V} \pm 0.2 \text{ V}$	2.2	3.2	5	1.5	5.7	
			$3.3 \text{ V} \pm 0.3 \text{ V}$	1.8	2.6	4.1	1.3	4.5	

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $C_L = 15$  pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V	48			30		MHz
			$1.2\text{ V} \pm 0.1\text{ V}$	112			120		
			$1.5\text{ V} \pm 0.1\text{ V}$	151			160		
			$1.8\text{ V} \pm 0.15\text{ V}$	194			220		
			$2.5\text{ V} \pm 0.2\text{ V}$	248			250		
			$3.3\text{ V} \pm 0.3\text{ V}$	280			260		
$t_{pd}$	CLK	Q	0.8 V	20.3					ns
			$1.2\text{ V} \pm 0.1\text{ V}$	5	8.7	13.6	3.9	15.6	
			$1.5\text{ V} \pm 0.1\text{ V}$	4.1	6.3	9.3	3.1	10.7	
			$1.8\text{ V} \pm 0.15\text{ V}$	3.3	4	7.6	2.4	8.7	
			$2.5\text{ V} \pm 0.2\text{ V}$	2.6	3.6	5.5	1.9	6.3	
			$3.3\text{ V} \pm 0.3\text{ V}$	2.2	3	4.5	1.6	5	

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $C_L = 30$  pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V	24			20		MHz
			$1.2\text{ V} \pm 0.1\text{ V}$	72			80		
			$1.5\text{ V} \pm 0.1\text{ V}$	100			100		
			$1.8\text{ V} \pm 0.15\text{ V}$	127			140		
			$2.5\text{ V} \pm 0.2\text{ V}$	185			210		
			$3.3\text{ V} \pm 0.3\text{ V}$	266			260		
$t_{pd}$	CLK	Q	0.8 V	27.2					ns
			$1.2\text{ V} \pm 0.1\text{ V}$	7	11.5	17.3	5.9	24	
			$1.5\text{ V} \pm 0.1\text{ V}$	5.7	8.3	13.3	4.6	15.9	
			$1.8\text{ V} \pm 0.15\text{ V}$	4.7	6.7	11.3	3.8	13	
			$2.5\text{ V} \pm 0.2\text{ V}$	3.7	4.9	7.8	2.9	9	
			$3.3\text{ V} \pm 0.3\text{ V}$	3.2	4.1	6.3	2.6	7.2	

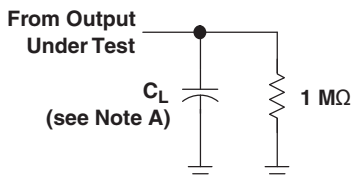
## OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	$f = 10$ MHz	0.8 V	2.5	pF
		$1.2\text{ V} \pm 0.1\text{ V}$	2.5	
		$1.5\text{ V} \pm 0.1\text{ V}$	2.5	
		$1.8\text{ V} \pm 0.15\text{ V}$	2.5	
		$2.5\text{ V} \pm 0.2\text{ V}$	3	
		$3.3\text{ V} \pm 0.3\text{ V}$	3	

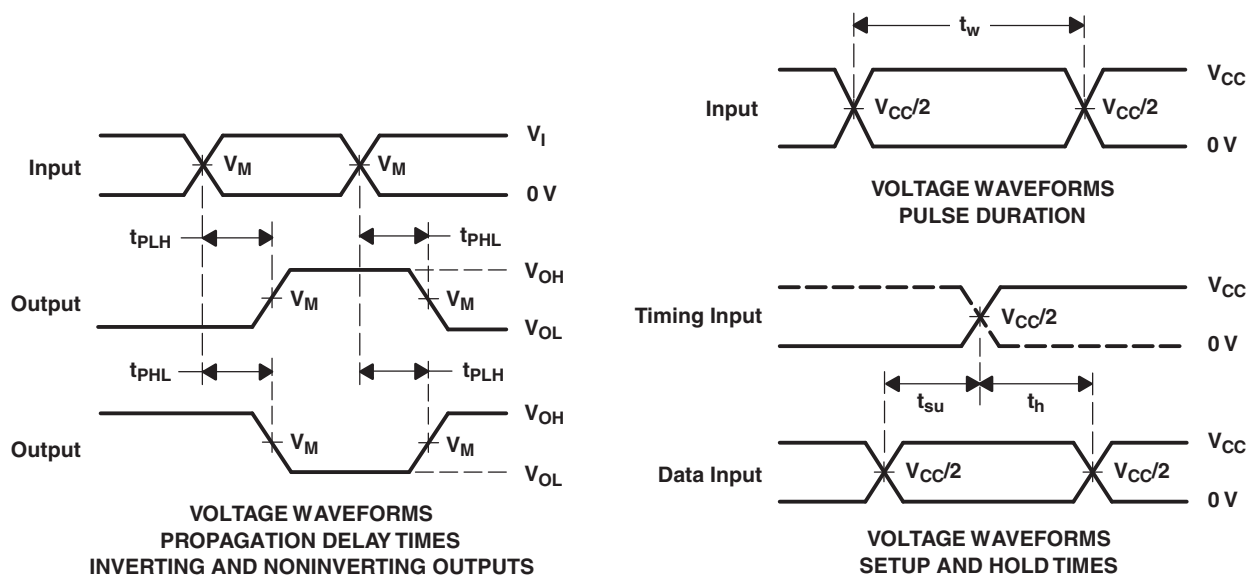


**PARAMETER MEASUREMENT INFORMATION  
(Propagation Delays, Setup and Hold Times, and Pulse Width)**



LOAD CIRCUIT

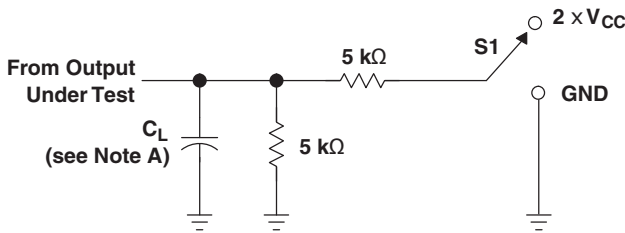
	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V} \pm 0.1\text{ V}$	$V_{CC} = 1.5\text{ V} \pm 0.1\text{ V}$	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ , for propagation delays  $t_r/t_f = 3\text{ ns}$ , for setup and hold times and pulse width  $t_r/t_f = 1.2\text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- F. All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

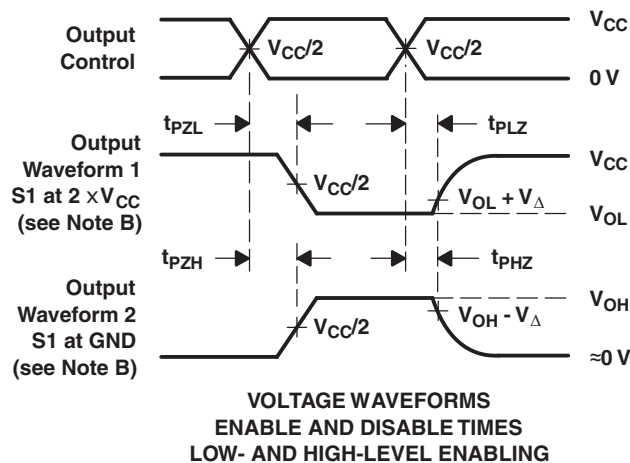
**PARAMETER MEASUREMENT INFORMATION  
(Enable and Disable Times)**



TEST	S1
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

**LOAD CIRCUIT**

	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V}$ $\pm 0.1\text{ V}$	$V_{CC} = 1.5\text{ V}$ $\pm 0.1\text{ V}$	$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$
$V_{\Delta}$	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r/t_f = 3\text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. All parameters and waveforms are not applicable to all devices.

**Figure 4. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74AUP2G79DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AUP2G79DQER	ACTIVE	X2SON	DQE	8	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AUP2G79RSER	ACTIVE	UQFN	RSE	8	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AUP2G79YFPR	ACTIVE	DSBGA	YFP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G79DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUP2G79DQER	X2SON	DQE	8	5000	180.0	8.4	1.17	1.67	0.73	4.0	8.0	Q1
SN74AUP2G79RSER	UQFN	RSE	8	5000	180.0	8.4	1.6	1.6	0.66	4.0	8.0	Q2
SN74AUP2G79YFPR	DSBGA	YFP	8	3000	178.0	9.2	0.9	1.75	0.6	4.0	8.0	Q1

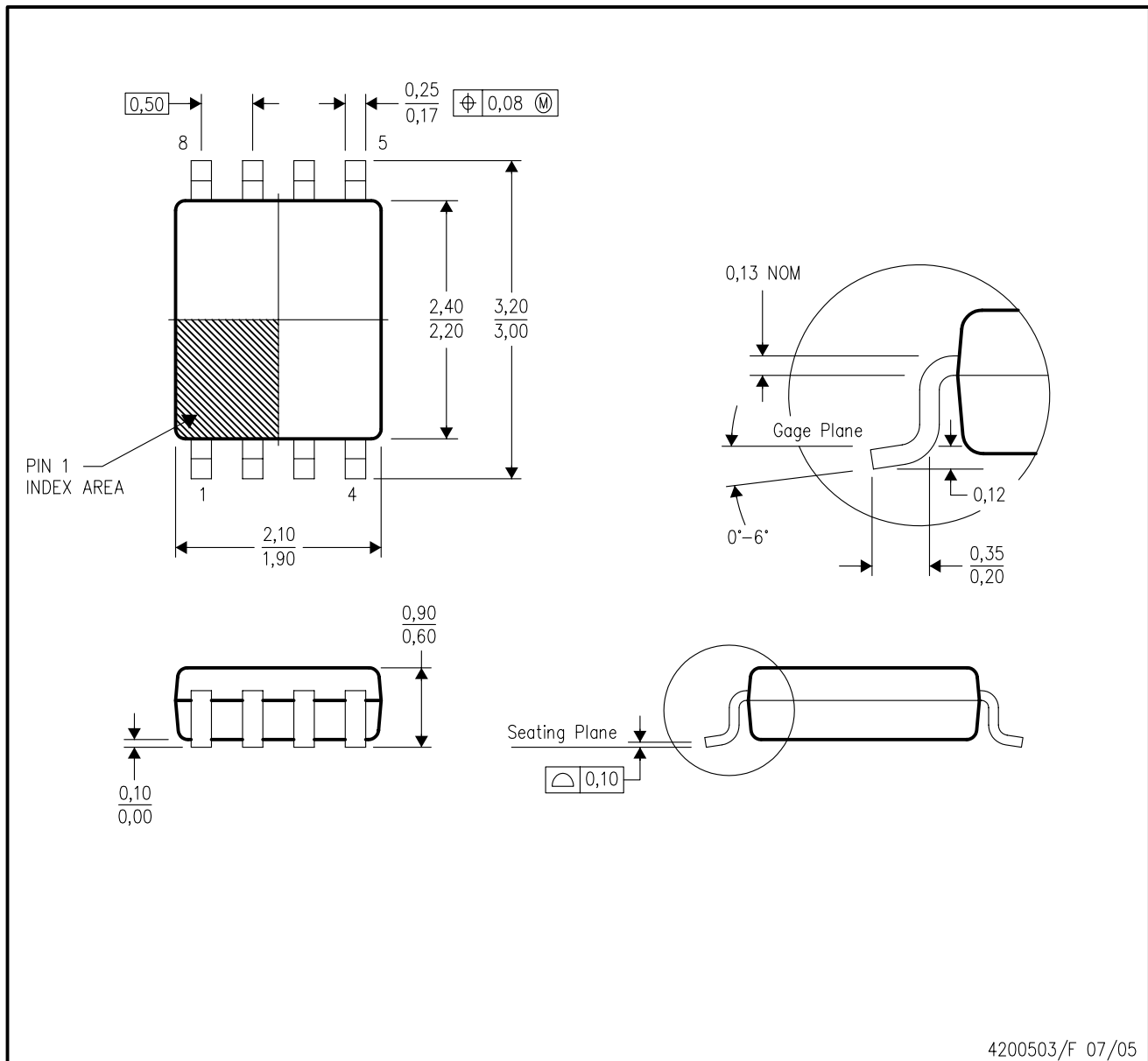
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G79DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74AUP2G79DQER	X2SON	DQE	8	5000	202.0	201.0	28.0
SN74AUP2G79RSER	UQFN	RSE	8	5000	202.0	201.0	28.0
SN74AUP2G79YFPR	DSBGA	YFP	8	3000	220.0	220.0	35.0

DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - Falls within JEDEC MO-187 variation CA.

DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)

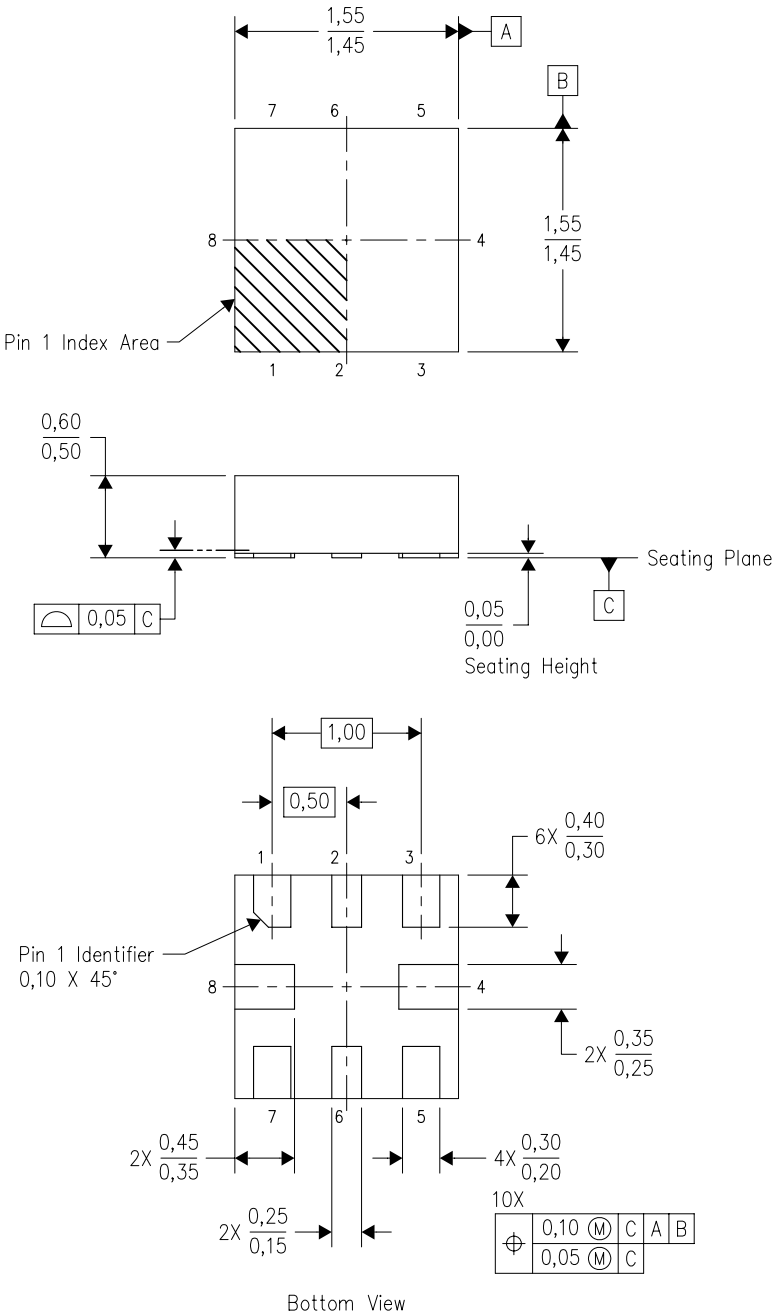


4210064/C 04/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RSE (S-PUQFN-N8)

PLASTIC QUAD FLATPACK NO-LEAD



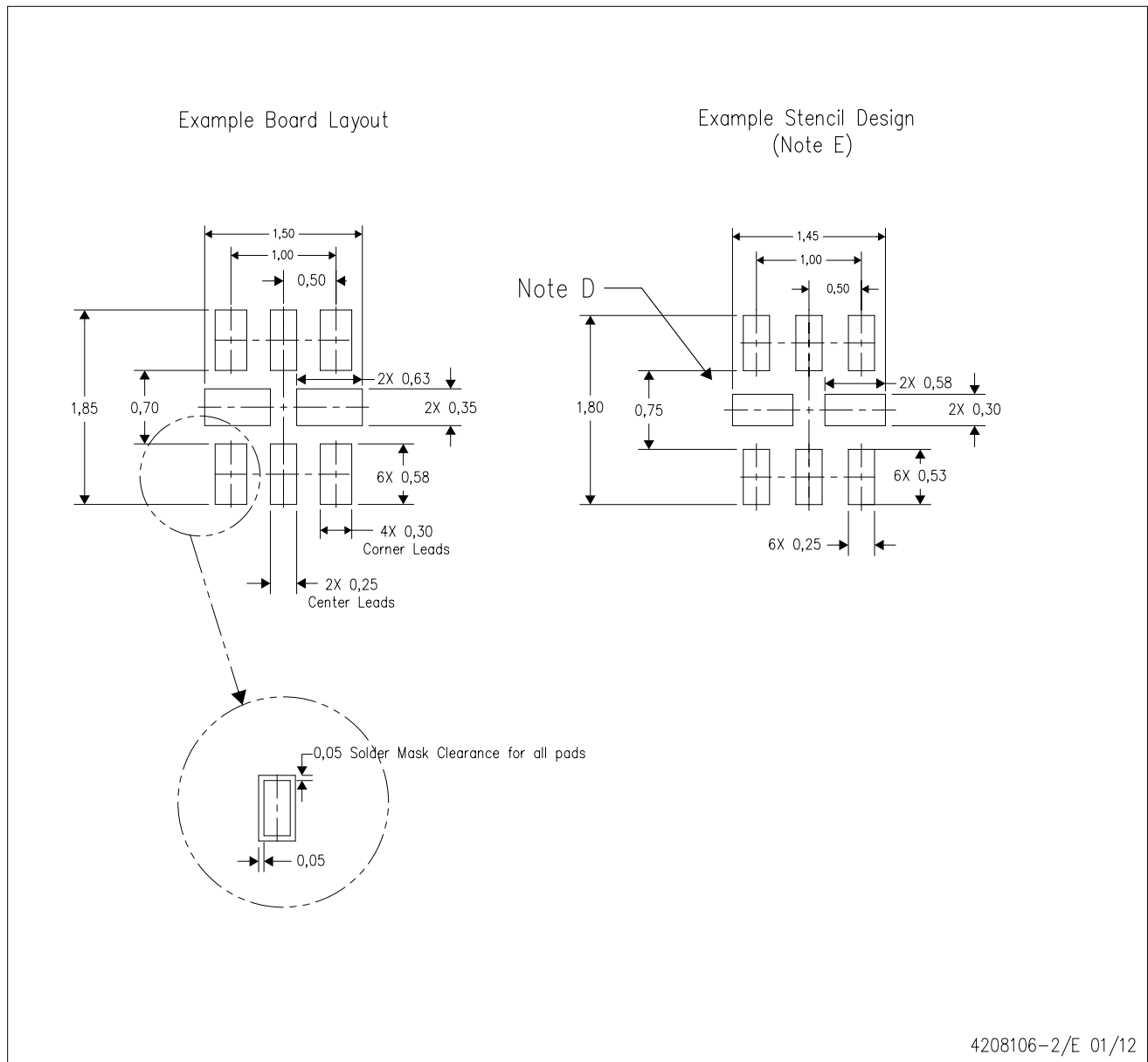
4207268-2/D 01/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - D. This package complies to JEDEC MO-288 variation UECD.



RSE (S-PUQFN-N8)

PLASTIC QUAD FLATPACK NO-LEAD

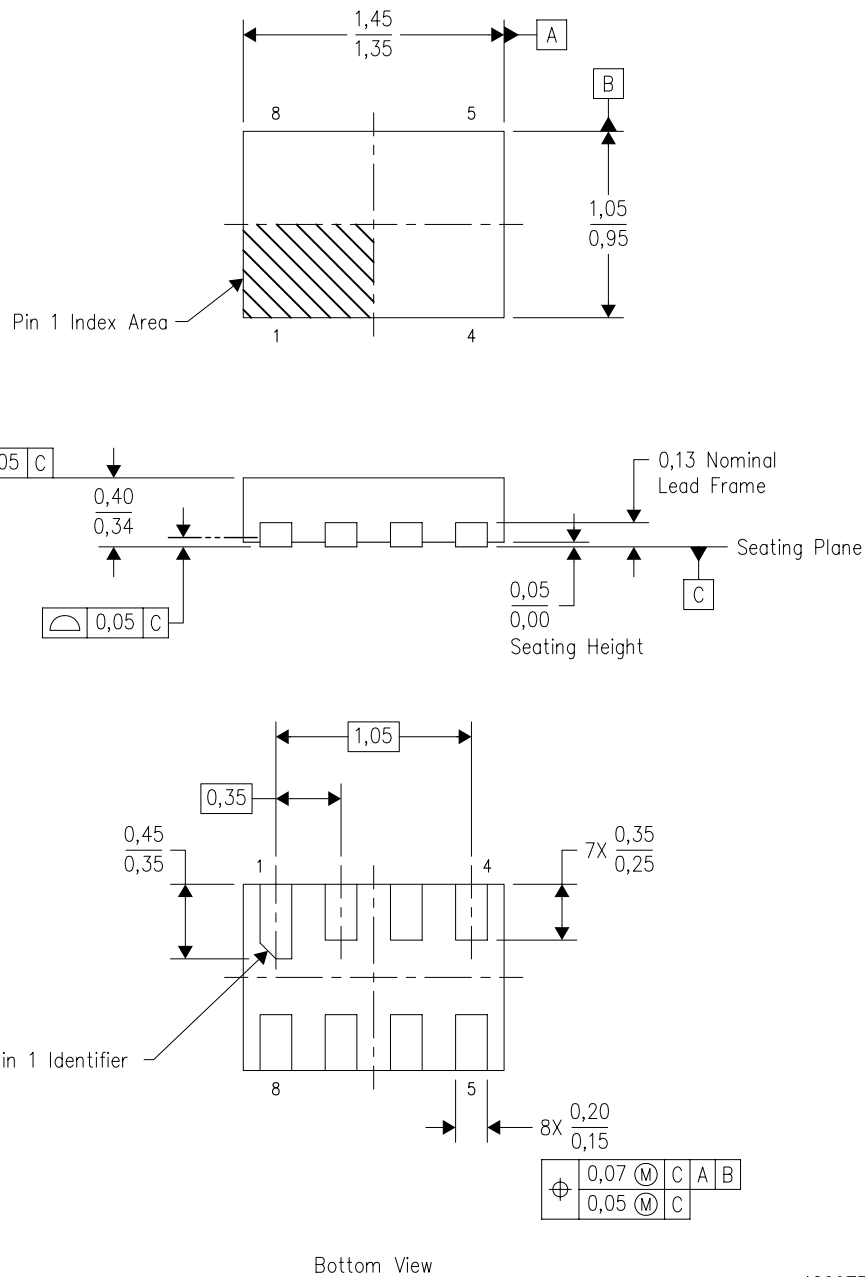


4208106-2/E 01/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
  - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
  - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DQE (R-PX2SON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



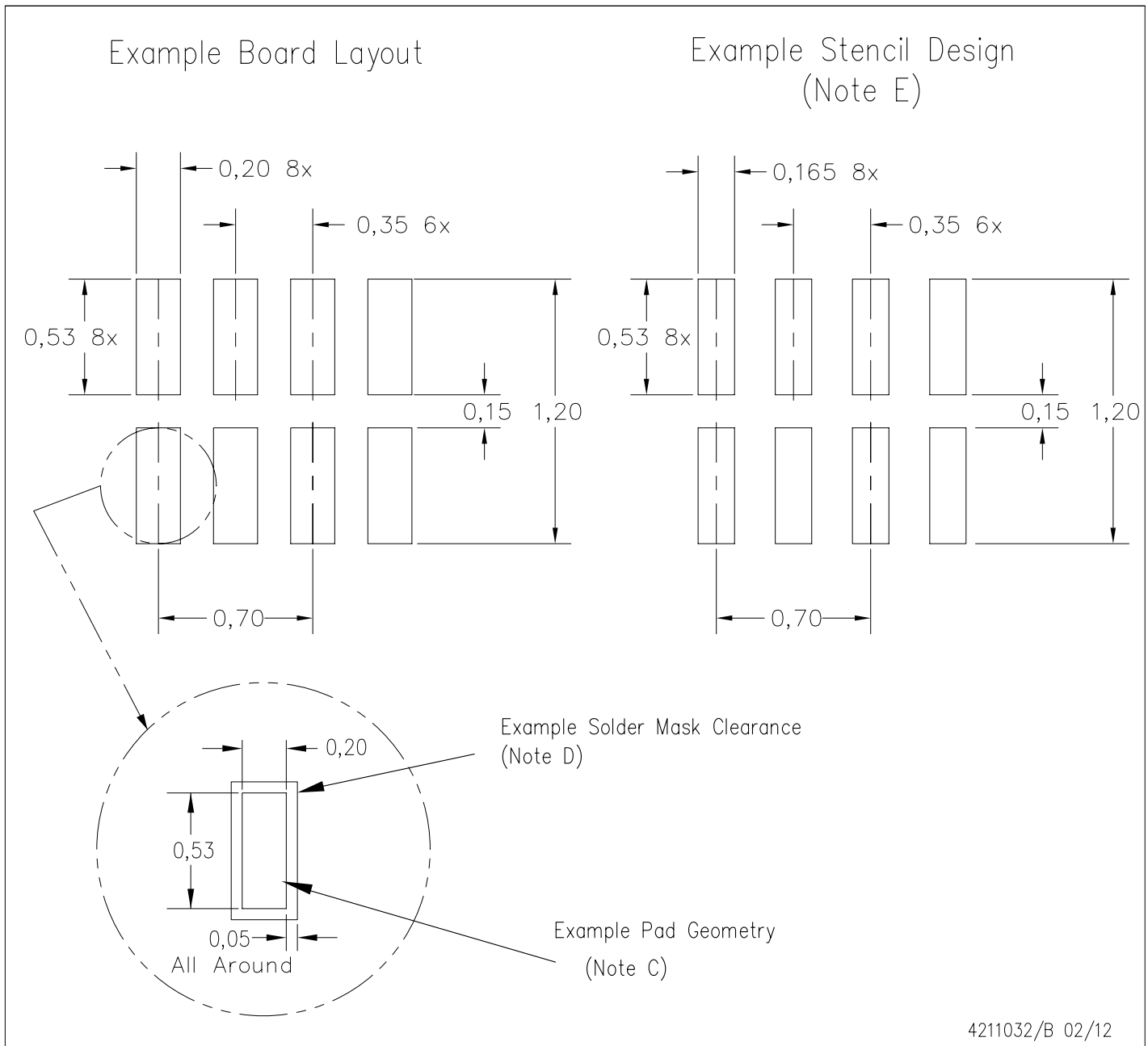
Bottom View

4209779/B 10/2008

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - SON (Small Outline No-Lead) package configuration.
  - This package complies to JEDEC MO-287 variation X2EAF.

DQE (R-PX2SON-N8)

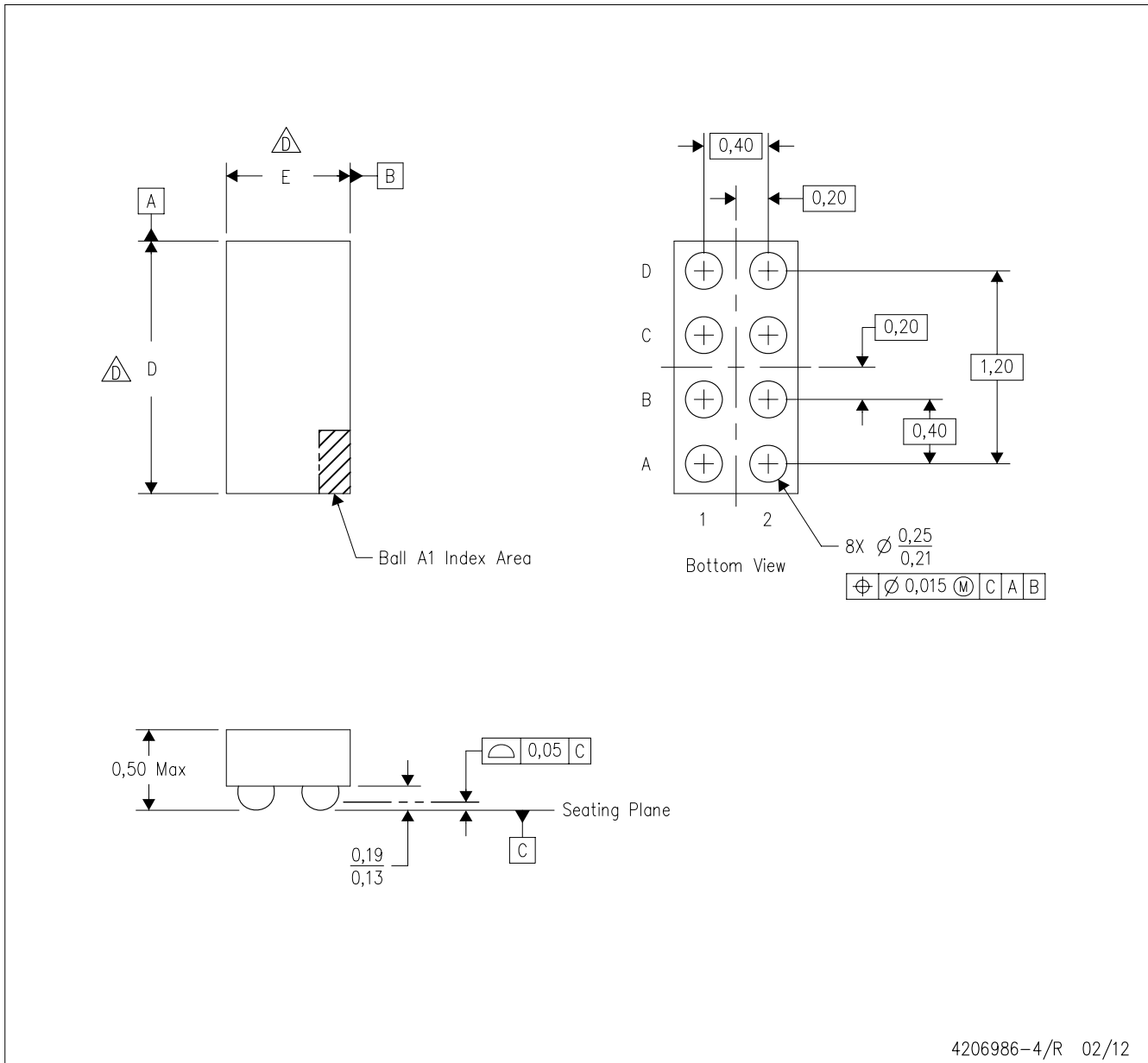
PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads. If 2 mil solder mask is outside PCB vendor capability, it is advised to omit solder mask.
  - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
  - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - G. Over-printing land for acceptable area ratio is not viable due to land width and bridging potential. Customer may further reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.
  - H. Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
  - I. Component placement force should be minimized to prevent excessive paste block deformation.

YFP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY

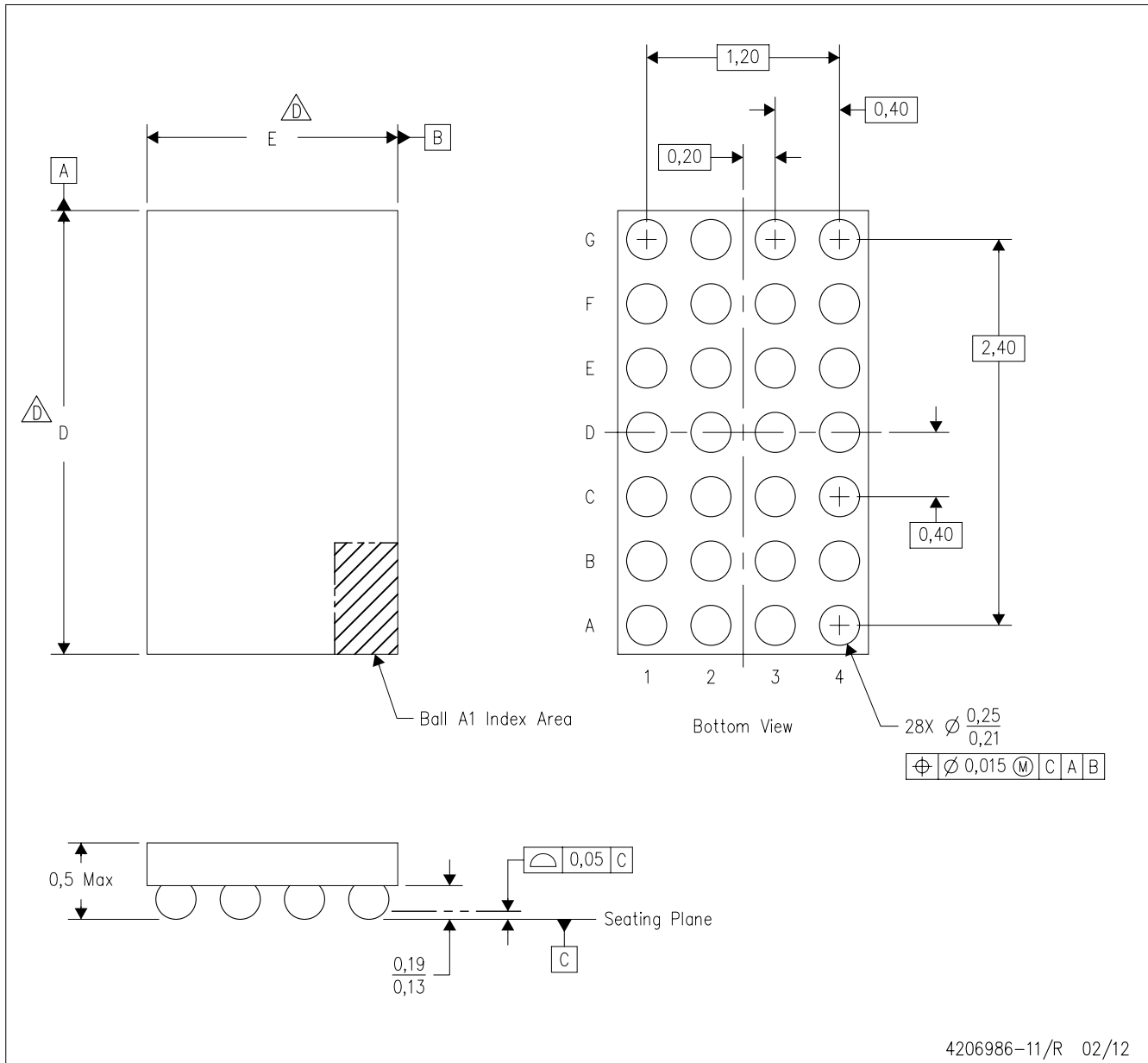


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - $\triangle D$  The package size (Dimension D and E) of a particular device is specified in the device Product Data Sheet version of this drawing, in case it cannot be found in the product data sheet please contact a local TI representative.
  - E. Reference Product Data Sheet for array population.  
2 x 4 matrix pattern is shown for illustration only.
  - F. This package contains Pb-free balls.

NanoFree is a trademark of Texas Instruments

YFP (R-XBGA-N28)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
  - E. This package contains Pb-free balls.

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